






















Layer construction MSL RAD Front-End-Electronics, TFLEX

		nominal thickness		
		micron	micron	micron
Top Soldermask				50
Top Copper Layer 01, 17+25				50
Rigid Base				150
No-Flow Prepreg 2 x 106				100
Coverlay 25/25			50	50
Copper Plane Layer 02			17	17
Outer Flex Base			50	50
Adhesive		electroless Sn	50	50
Coverlay 25/25		50	50	50
Copper Plane Layer 03		17	17	17
Inner Flex Base		50	50	50
Copper Plane Layer 04		17	17	17
Coverlay 25/25		50	50	50
Adhesive		electroless Sn	50	50
Outer Flex Base			50	50
Copper Plane Layer 05			17	17
Coverlay 25/25			50	50
No-Flow Prepreg 2 x 106				100
Rigid Base				150
Bottom Copper Layer 06, 17+25				50
Bottom Soldermask				50

nominal total thickness Omnetics connector: **184**

nominal total thickness layer 02 to 05: **518**

nominal total thickness **1218**

Rigid Base:	Polyimide-Glass-(GIJ)
No-Flow Prepreg	Polyimide-Glass-(GIJ)
Coverlay	25 micron Polyimide, 25 micron Acrylic-Adhesive
Flex Base	50 micron Polyimide, adhesiveless
Adhesive	Acrylic Adhesive
Finish	electroless Sn, incl. Omnetics connector
Soldermask	Probimer 65
thickness tolerance	+/- 10%
Fabrication	IPC-60132, Class III